

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11696801
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Total Attachments: 2
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FAIRCHILD SEMICONDUCTOR CORPORATION

Assignment

As a below named inventor or joint inventor of an invention or improvement entitled:

POWER SYSTEM MODULE AND METHOD OF FABRICATING THE SAME

for which I have executed an application for Letters Patent of the United States of America, on an even date herewith; and

WHEREAS, FAIRCHILD KOREA SEMICONDUCTOR, LTD., a Large Entity, organized and existing under the laws of the Republic of Korea, having a principal place of business at (420-711) 82-3 Dodang-Dong, Wonmi-gu, Bucheon-si, Gyeonggi-do, Korea, is desirous of obtaining the entire right, title and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I have sold, assigned, transferred, and set over, and by these presents do hereby sell, assign, transfer and set over, unto said FAIRCHILD KOREA SEMICONDUCTOR, LTD., its successors, legal representatives, and assigns, my entire right, title and interest in, to, and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuation applications thereof, and all Letters Patent of the United States of America which may be granted thereof and all reissues and extensions hereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, including all rights of priority, all rights to publish cautionary notices reserving ownership of said invention, all rights to register said invention in appropriate registries, and all Letters Patent which may be granted for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and I hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to said FAIRCHILD KOREA SEMICONDUCTOR, LTD., its successors, legal representatives, and assigns, in accordance with the terms of this instrument.

And I hereby covenant that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

And I hereby further covenant and agree that I will communicate to said FAIRCHILD KOREA SEMICONDUCTOR, LTD., its successors, legal representatives, and assigns, any fact known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisions, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid said FAIRCHILD KOREA SEMICONDUCTOR, LTD., its successors, legal representatives, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

